

3. (Amended) A semiconductor device having a plurality of pyramidal bump electrodes with a sharp tip, formed of conductive materials filling up etched pyramidal holes on a base material having a crystal orientation plane, respectively bonded by thermal compression onto pad electrodes arranged on a semiconductor chip.

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4. (Amended) A semiconductor device having a plurality of pyramidal bump electrodes with a sharp tip, formed of conductive materials filling up etched pyramidal holes on a base material having a crystal orientation plane, respectively bonded by thermal compression onto pad electrodes arranged on a semiconductor chip so that said pyramidal bump electrodes and said pad electrodes can form an alloy at the junctions by said thermal compression.

5. (Amended) A semiconductor device having a plurality of pyramidal bump electrodes with a sharp tip, formed of conductive materials filling up etched pyramidal holes on a base material having a crystal orientation plane, respectively bonded onto rewired metal conduction pads that are electrically connected to pad electrodes arranged on a semiconductor chip.

B2

9. (Amended) A mounting structure in a semiconductor device having a plurality of pyramidal bump electrodes with a

sharp tip, formed of conductive materials filling up etched pyramidal holes on a base material having a crystal orientation plane, respectively bonded through an anisotropic conduction film onto pad electrodes arranged on a semiconductor chip, said mounting structure enabling said semiconductor device to be mounted on a substrate by respectively bonding said pyramidal bump electrodes onto terminals formed on said substrate.

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Wnt

10. (Amended) A mounting structure in a semiconductor device having a plurality of pyramidal bump electrodes with a sharp tip, formed of conductive materials filling up etched pyramidal holes on a base material having a crystal orientation plane, respectively bonded by thermal compression onto pad electrodes arranged on a semiconductor chip, said mounting structure enabling said semiconductor device to be mounted on a substrate by respectively bonding said pyramidal bump electrodes onto terminals formed on said substrate.

11. (Amended) A mounting structure in a semiconductor device having a plurality of pyramidal bump electrodes with a sharp tip, formed of conductive materials filling up etched pyramidal holes on a base material having a crystal orientation plane, respectively bonded by thermal compression onto pad electrodes arranged on a semiconductor chip so that said pyramidal bump electrodes and said pad electrodes can

form an alloy at the junctions by said thermal compression, said mounting structure enabling said semiconductor device to be mounted on a substrate by respectively bonding said pyramidal bump electrodes onto terminals formed on said substrate.

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bent

12. (Amended) A mounting structure in a semiconductor device having a plurality of pyramidal bump electrodes with a sharp tip, formed of conductive materials filling up etched pyramidal holes on a base material having a crystal orientation plane, respectively bonded onto pad electrodes arranged on semiconductor chip, said mounting structure enabling said semiconductor device to be mounted on a substrate by respectively soldering said pyramidal bump electrodes onto terminals formed on said substrate.

13. (Amended) A mounting structure in a semiconductor device having a plurality of pyramidal bump electrodes with a sharp tip, formed of conductive materials filling up etched pyramidal holes on a base material having a crystal orientation plane, respectively bonded through an anisotropic conduction film onto pad electrodes arranged on a semiconductor chip, said mounting structure enabling said semiconductor device to be mounted on a substrate by respectively soldering said pyramidal bump electrodes onto terminals formed on said substrate.

14. (Amended) A mounting structure in a semiconductor device having a plurality of pyramidal bump electrodes with a sharp tip, formed of conductive materials filling up etched pyramidal holes on a base material having a crystal orientation plane, respectively bonded by thermal compression onto pad electrodes arranged on a semiconductor chip, said mounting structure enabling said semiconductor device to be mounted on a substrate by respectively soldering said pyramidal bump electrodes onto terminals formed on said substrate.

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15. (Amended) A mounting structure in a semiconductor device having a plurality of pyramidal bump electrodes with a sharp tip, formed of conductive materials filling up etched pyramidal holes on a base material having a crystal orientation plane, respectively bonded by thermal compression onto pad electrodes arranged on a semiconductor chip so that said pyramidal bump electrodes and said pad electrodes can form an alloy at the junctions by said thermal compression, said mounting structure enabling said semiconductor device to be mounted on a substrate by respectively soldering said pyramidal bump electrodes onto terminals formed on said substrate.

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16. (Amended) A mounting structure in a semiconductor device having a plurality of pyramidal bump electrodes with a sharp tip, formed of conductive materials filling up etched pyramidal holes on a base material having a crystal orientation plane, respectively bonded onto pad electrodes arranged on a semiconductor chip, said mounting structure enabling said semiconductor device to be mounted on a substrate by respectively bonding said pyramidal bump electrodes onto terminals formed on said substrate and by bonding said semiconductor device to said substrate with an adhesive.

17. (Amended) A mounting structure in a semiconductor device having a plurality of pyramidal bump electrodes with a sharp tip, formed of conductive materials filling up etched pyramidal holes on a base material having a crystal orientation plane, respectively bonded through an anisotropic conduction film onto pad electrodes arranged on a semiconductor chip, said mounting structure enabling said semiconductor device to be mounted on a substrate by respectively bonding said pyramidal bump electrodes onto terminals formed on said substrate and by bonding said semiconductor device to said substrate with an adhesive.

18. (Amended) A mounting structure in a semiconductor device having a plurality of pyramidal bump electrodes with a

sharp tip, formed of conductive materials filling up etched pyramidal holes on a base material having a crystal orientation plane, respectively bonded by thermal compression onto pad electrodes arranged on a semiconductor chip, said mounting structure enabling said semiconductor device to be mounted on a substrate by respectively bonding said pyramidal bump electrodes onto terminals formed on said substrate and by bonding said semiconductor device to said substrate with an adhesive.

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19. (Amended) A mounting structure in a semiconductor device having a plurality of pyramidal bump electrodes with a sharp tip, formed of conductive materials filling up etched pyramidal holes on a base material having a crystal orientation plane, respectively bonded by thermal compression onto pad electrodes arranged on a semiconductor chip so that said pyramidal bump electrodes and said pad electrodes can form an alloy at the junctions by said thermal compression, said mounting structure enabling said semiconductor device to be mounted on a substrate by respectively bonding said pyramidal bump electrodes onto terminals formed on said substrate and by bonding said semiconductor device to said substrate with an adhesive.
